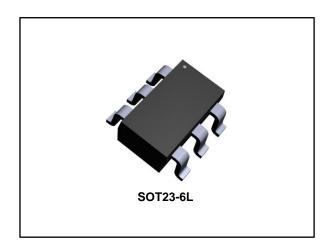


Secondary protection for VDSL2 and G.FAST lines

Datasheet - production data



Features

- High surge capability to comply with GR-1089 and ITU-T K20/21/45
- Keeps peak power capability at high temperature
- Voltages: 8, 12, 16 and 24 V
- Low capacitance device: C_{typ} = 0.95 pF
- RoHS package
- Low leakage current: 50 nA at 25 °C

Complies with the following standards

Refer to Section 2: "Schematics".

- Telcordia GR-1089
 - 2.5 kV 2/10 μs 500 A 2/10 μs
 - AC power fault tests
- ITU-T K20/21/45
 - 6 kV 10/700 μs 150 A 5/310 μs
 - power induction and contact tests
- IEC 61000-4-2, level 4
 - 15 kV (air discharge)
 - 8 kV (contact discharge)
- IEC 61000-4-5, level 2
 - 1 kV, 42 Ω
- MIL STD 883G-Method 3015-7: Class 3
 - 8 kV (human body model)

Description

DSL05 is designed to protect DSL line drivers against surges defined in worldwide telecommunication standards. This device protects line drivers of various systems such as xDSL and G.FAST. The low capacitance makes it suitable from ADSL to G.FAST data rates.

DSL05 is able to survive severe conditions even when used with downgraded or oscillating gas tube.

This device is packaged in a SOT23-6L.

Figure 1: Functional diagram

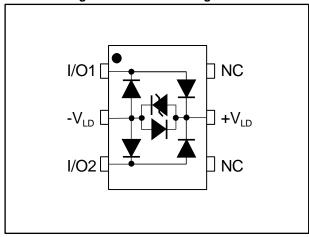


Table 1: Device summary

Order code	V _{RM} (V)
DSL05-008SC6	8
DSL05-012SC6	12
DSL05-016SC6	16
DSL05-024SC6	24

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Characteristics DSL05

1 Characteristics

Table 2: Absolute ratings (T_{amb} = -40 to 85 °C)

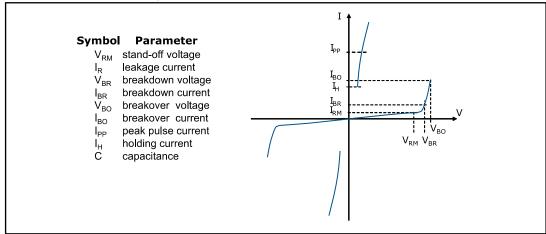
Symbol	Parameter	Value	Unit	
I _{pp}	Peak pulse current	30	Α	
dl/dt	Critical rate of on-state current rise	1000	A/µs	
T _{stg}	Storage junction temperature range	55.4450	00	
Tj	Maximum operating junction temperature -55 to +150 °C			°C
TL	Maximum temperature for soldering during 10 s 260			°C

Table 3: Electrical characteristics (T_{amb} = 25 °C, pin 1 to pin 3)

I _{RM} at V _{RM}						V _{BR} at 1 mA	V _{BO}	IH	C ⁽¹⁾	ΔC ⁽²⁾
Ouder sode	Тур.	Max.	Тур.	Max.		Min.	Max.	Тур.	Max.	Тур.
Order code				85 °C						
		n	A		٧	V	٧	mA	pF	pF
DSL05-008SC6	0.1	50	7	100	8	9.5	15	50	1.5	0.25
DSL05-012SC6	0.1	50	7	100	12	12.8	18	10	1.5	0.25
DSL05-016SC6	0.1	50	7	100	16	18	25	30	1.5	0.25
DSL05-024SC6	0.1	50	7	100	24	25.5	31	50	1.5	0.25

Notes:

Figure 2: Electrical characteristics definitions



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 $^{^{(1)}}$ Test conditions: $V_R = 2 V$ bias, $V_{RMS} = 1 V$, f = 1 MHz

 $[\]ensuremath{^{(2)}}\text{Measured}$ between 1 V and $\ensuremath{V_{\text{RM}}}$

DSL05 Characteristics

1.1 Characteristics (curves)

Figure 3: Peak pulse power dissipation versus

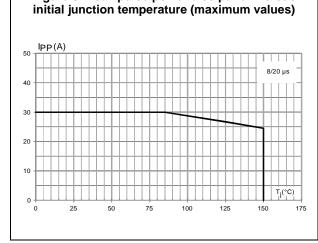


Figure 4: Leakage current versus junction temperature

Figure 5: Junction capacitance versus reverse voltage

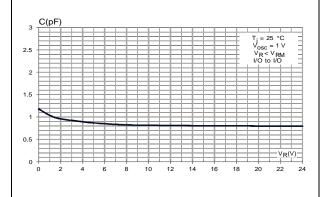


Figure 6: Junction capacitance versus junction temperature

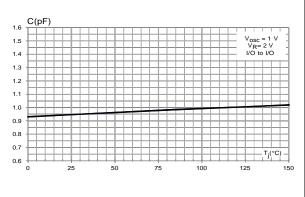
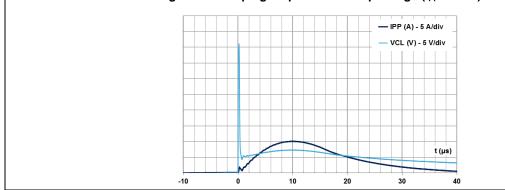


Figure 7: Clamping response to 8/20 μ s surge ($I_{pp} = 10 \text{ A}$)



Schematics DSL05

2 Schematics

Figure 8: xDSL and G.FAST schematic for CPE applications

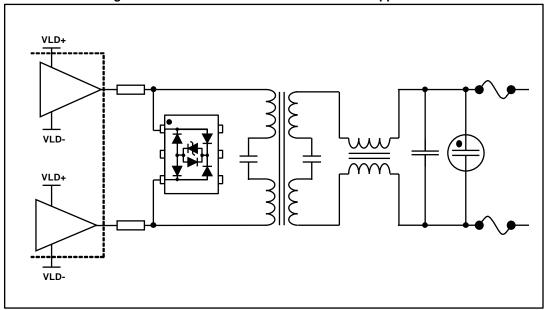
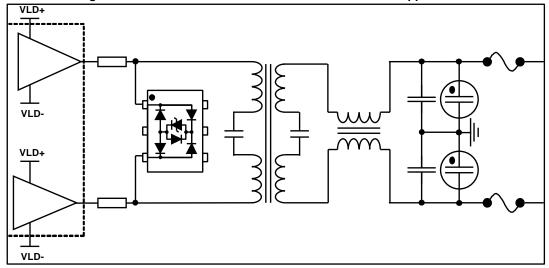


Figure 9: xDSL and G.FAST schematic for infrastructure applications



On topologies given in *Figure 8: "xDSL and G.FAST schematic for CPE applications"* and *Figure 9: "xDSL and G.FAST schematic for infrastructure applications"*, +VLD and -VLD may not be connected.

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DSL05 Package information

3 Package information

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK® packages, depending on their level of environmental compliance. ECOPACK® specifications, grade definitions and product status are available at: **www.st.com**. ECOPACK® is an ST trademark.

- Epoxy meets UL 94,V0
- Lead-free package

3.1 SOT23-6L package information

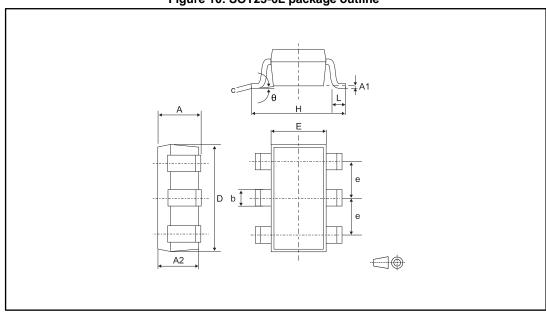


Figure 10: SOT23-6L package outline

Table 4: SOT23-6L package mechanical data

			ı	Dimensions		
Ref.	Millimeters		Inches			
	Min.	Тур.	Max.	Min.	Тур.	Max.
А	0.9		1.45	0.0354		0.0571
A1	0		0.15	0		0.0059
A2	0.9		1.3	0.0354		0.0512
b	0.30		0.5	0.0118		0.0197
С	0.09		0.2	0.0035		0.0079
D	2.8		3.05	0.1102		0.1201
Е	1.5		1.75	0.0591		0.0689
е		0.95			0.0374	
Н	2.6		3	0.1024		0.1181
L	0.3		0.6	0.0118		0.0236
θ	0		10	0		0.3937



Package information DSL05

Figure 11: Footprint recommendations, dimensions in mm (inches)

0.60
(0.024)

1.20
(0.047)

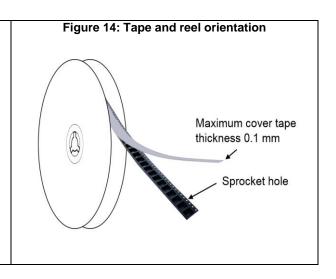
1.10
(0.043)

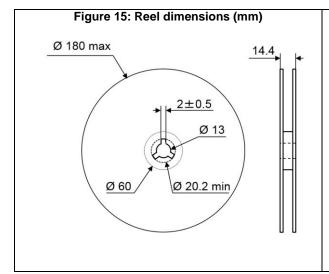
Figure 12: Marking layout (refer to ordering information table for marking)

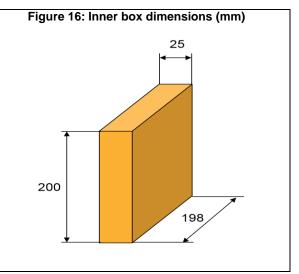
XXXXX

Pin 1 located according to EIA-481

Note: Pocket dimensions are not on scale Pocket shape may vary depending on package







DSL05 Package information

Figure 17: Tape and reel outline

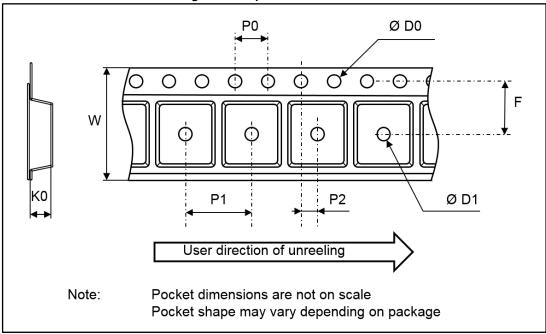


Table 5: Tape and reel mechanical data

	Dimensions					
Ref.	Millimeters					
	Min.	Тур.	Max.			
P1	3.9	4	4.1			
P0	3.9	4	4.1			
D0	1.45	1.5	1.6			
D1	1					
F	3.45	3.5	3.55			
K0	1.3	1.4	1.6			
P2	1.95	2	2.05			
W	7.9	8	8.3			

Package information DSL05

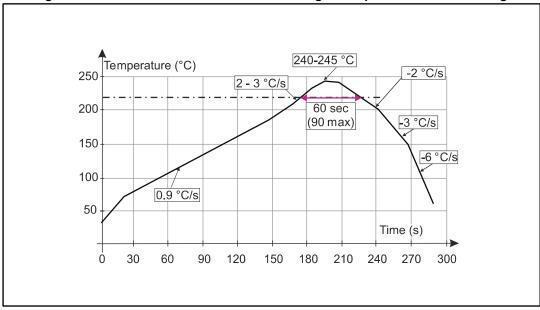


Figure 18: ST ECOPACK® recommended soldering reflow profile for PCB mounting



Minimize air convection currents in the reflow oven to avoid component movement. Maximum soldering profile corresponds to the latest IPC/JEDEC J-STD-020.

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DSL05 Ordering information

4 Ordering information

Figure 19: Ordering information scheme

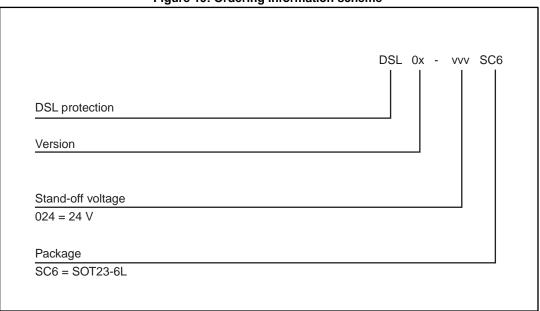


Table 6: Ordering information

Order code	Marking	Package	Weight	Base qty.	Delivery mode
DSL05-008SC6	D508				
DSL05-012SC6	D512	SOT23-6L	44 ==	0000	Tana and mad
DSL05-016SC6	D516		14 g	3000	Tape and reel
DSL05-024SC6	D524				

5 Revision history

Table 7: Document revision history

Date	Revision	Changes
05-Jul-2016	1	Initial release.
03-Oct-2016	2	Updated Table 3: "Electrical characteristics (Tamb = 25 °C, pin 1 to pin 3)".
22-Aug-2017	3	Added RPN DSL05-016SC6. Updated Table 3: "Electrical characteristics (Tamb = 25 °C, pin 1 to pin 3)" and Figure 4: "Leakage current versus junction temperature".

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